

Date: May 6, 2022
Time: 12:00 PM ET
Presenter: Jie Xiu, PhD.



[Registration Link](#)

Advanced Packaging in Hyperscale Data Center Applications

Abstract:

Advanced Packaging technologies including Silicon and Silicon photonics are key enablers for scaling Hyperscale Data Center. This talk will discuss the roadmap of technology building blocks with a focus on increasing in performance while reducing power per Gbps. Challenges toward device integration, reliability and industry ecosystem collaboration will also be elaborated.

Bio:

Jie Xue

Vice President, Technology & Quality
Cisco Systems, Inc



Jie Xue leads Cisco's Technology and Quality organization, a global team responsible for pathfinding, developing, and executing technology innovations to enable all Cisco networking product portfolio. Jie oversees development of leading edge technologies for Si-Photonics, Advanced Si, ASICs, PCBs, Optics, memory, and complex interconnect technologies. Prior to joining Cisco, Jie held several management and engineering positions at Motorola, Inc., working on R&D and product development.

Jie is an IEEE Fellow, President of IEEE – Electronics Packaging Society (EPS) 2014-2015. She has published more than 90 technical papers, holds 15 patents. Jie holds a Bachelor of Science from Tsinghua University in Beijing, China and a Master of Science and PhD from Cornell University.

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Binghamton Chapter

